TIDA-00917 REV E1 Bill of Materials

Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
1	!PCB1	1		TIDA-00917	Any	Printed Circuit Board	
2	C1, C4, C18	3	4.7uF	GRM21BR71C475KA73L	MuRata	CAP, CERM, 4.7 µF, 16 V, +/- 10%, X7R, 0805	0805
3	C2, C5, C11, C13, C16, C19, C21, C30, C44, C45	10	0.1uF	C1608X7R1H104K080AA	TDK	CAP, CERM, 0.1 µF, 50 V, +/- 10%, X7R, 0603	0603
4	C3, C20	2	220pF	C0603C221K5RACTU	Kemet	CAP, CERM, 220 pF, 50 V, +/- 10%, X7R, 0603	0603
5	C6, C17, C22, C31	4	1uF	CL21B105KBFNNNE	Samsung Electro-Mechanics	CAP, CERM, 1 µF, 50 V, +/- 10%, X7R, 0805	0805
6	C7, C10, C15, C23, C29, C41, C42, C43	8	22uF	GRM32ER71E226KE15L	MuRata	CAP, CERM, 22 µF, 25 V, +/- 10%, X7R, 1210	1210
7	C8	1	0.01uF	GRM155R71C103KA01D	MuRata	CAP, CERM, 0.01 µF, 16 V, +/- 10%, X7R, 0402	0402
8	C9	1	100pF	C0402C101J3GACTU	Kemet	CAP, CERM, 100 pF, 25 V, +/- 5%, C0G/NP0, 0402	0402
9	C12, C14, C28, C33	4	1uF	C3216X7R2A105M160AA	TDK	CAP, CERM, 1 µF, 100 V, +/- 20%, X7R, 1206	1206
10	C24, C25, C26, C27	4	10uF	UMK325AB7106KM-T	Taiyo Yuden	CAP, CERM, 10 µF, 50 V, +/- 10%, X7R, 1210	1210
11	C32, C35	2	2200pF	885012205027	Wurth Elektronik	CAP, CERM, 2200 pF, 16 V, +/- 10%, X7R, 0402	0402
12	C34, C36, C37, C38	4	0.22uF	GRM188R71H224KAC4D	MuRata	CAP, CERM, 0.22 µF, 50 V, +/- 10%, X7R, 0603	0603
13	C39, C40	2	0.015uF	C0603C153K1RACTU	Kemet	CAP, CERM, 0.015 µF, 100 V, +/- 10%, X7R, 0603	0603
14	D1, D2, D5, D6	4	1200V	STTH112A	STMicroelectronics	Diode, Ultrafast, 1200 V, 1 A, SMA	SMA
15	D3, D7	2	12V	MMSZ5242BS-7-F	Diodes Inc.	Diode, Zener, 12 V, 200 mW, SOD-323	SOD-323
16	D4, D8	2	30V	BAT54WS-7-F	Diodes Inc.	Diode, Schottky, 30 V, 0.2 A, SOD-323	SOD-323
17	D9, D11	2	1.1V @ 100mA	BZX84J-B15,115	NXP Semiconductors	DIODE ZENER 15V 550MW SOD323F	SC-90, SOD-323F
18	D10	1	20V	MBR0520LT1G	ON Semiconductor	Diode, Schottky, 20 V, 0.5 A, SOD-123	SOD-123
19	D12, D13, D14, D15	4	18V	SMAJ18CA	Littelfuse	Diode, TVS, Bi, 18 V, 400 W, SMA	SMA
20	FID1, FID2, FID3	3		N/A	N/A	Fiducial mark. There is nothing to buy or mount.	Fiducial
21	J1	1		22-23-2061	Molex	Header, 2.54 mm, 6x1, Tin, TH	Header, 2.54mm, 6x1, TH
22	J2, J3, J5, J6	4		22-23-2021	Molex	Header, 2.54mm, 2x1, Vertical, TH	Header, 2.54mm, 2x1, TH
23	J4	1		22-23-2031	Molex	Header, 2.54 mm, 3x1, Tin, TH	Header, 2.54mm, 3x1, TH
24	L1, L2, L3, L4	4	11uH	B82789C0113N002	TDK	Coupled inductor, 11 µH, 0.3 A, 0.25 ohm, SMD	4.5x3.0x3.2mm
25	LBL1	1		THT-14-423-10	Brady	Thermal Transfer Printable Labels, 0.650" W x 0.200" H - 10,000 per roll	PCB Label 0.650"H x 0.200"W
26	Q1, Q3	2	80 V	MJD44H11RLG	ON Semiconductor	Transistor, NPN, 80 V, 8 A, AEC-Q101, DPAK	DPAK
27	Q2, Q4	2	80 V	MJD45H11RLG	ON Semiconductor	Transistor, PNP, 80 V, 8 A, DPAK	DPAK
28	R1, R13	2	10.0	CRCW060310R0FKEA	Vishay-Dale	RES, 10.0, 1%, 0.1 W, 0603	0603
29	R2, R14	2	1.00k	ERJ-6ENF1001V	Panasonic	RES, 1.00 k, 1%, 0.125 W, 0805	0805
30	R3, R4, R30	3	20.0k	CRCW040220K0FKED	Vishay-Dale	RES, 20.0 k, 1%, 0.063 W, 0402	0402
31	R5, R6, R10, R15, R16, R20	6	12.0	RC1206FR-0712RL	Yageo America	RES, 12.0, 1%, 0.25 W, 1206	1206

Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
32	R7, R8, R9, R11, R12, R17, R18, R19, R21, R22, R32, R33, R36, R37	14	0.3	CSRN2512FKR300	Stackpole Electronics Inc	RES, 0.3, 1%, 2 W, 2512	2512
33	R23, R26	2	100	CRCW0402100RFKED	Vishay-Dale	RES, 100, 1%, 0.063 W, 0402	0402
34	R24, R31	2	511	ERJ-8ENF5110V	Panasonic	RES, 511, 1%, 0.25 W, 1206	1206
35	R25, R27, R28, R29	4	10.0k	ERJ-3EKF1002V	Panasonic	RES, 10.0 k, 1%, 0.1 W, 0603	0603
36	R34, R35	2	0.01	WSLP1206R0100FEA	Vishay-Dale	RES, 0.01, 1%, 1 W, 1206	1206
37	TP1, TP2, TP3, TP4, TP9, TP10, TP11, TP12	8		5005	Keystone	Test Point, Compact, Red, TH	Red Compact Testpoint
38	U1, U2	2		ISO5852SDWR	Texas Instruments	2.5 / 5 A Isolated IGBT Gate Driver with Split Outputs and Active Safety Features, DW0016A	DW0016A

IMPORTANT NOTICE FOR TI DESIGN INFORMATION AND RESOURCES

Texas Instruments Incorporated ('TI") technical, application or other design advice, services or information, including, but not limited to, reference designs and materials relating to evaluation modules, (collectively, "TI Resources") are intended to assist designers who are developing applications that incorporate TI products; by downloading, accessing or using any particular TI Resource in any way, you (individually or, if you are acting on behalf of a company, your company) agree to use it solely for this purpose and subject to the terms of this Notice.

TI's provision of TI Resources does not expand or otherwise alter TI's applicable published warranties or warranty disclaimers for TI products, and no additional obligations or liabilities arise from TI providing such TI Resources. TI reserves the right to make corrections, enhancements, improvements and other changes to its TI Resources.

You understand and agree that you remain responsible for using your independent analysis, evaluation and judgment in designing your applications and that you have full and exclusive responsibility to assure the safety of your applications and compliance of your applications (and of all TI products used in or for your applications) with all applicable regulations, laws and other applicable requirements. You represent that, with respect to your applications, you have all the necessary expertise to create and implement safeguards that (1) anticipate dangerous consequences of failures, (2) monitor failures and their consequences, and (3) lessen the likelihood of failures that might cause harm and take appropriate actions. You agree that prior to using or distributing any applications that include TI products, you will thoroughly test such applications and the functionality of such TI products as used in such applications. TI has not conducted any testing other than that specifically described in the published documentation for a particular TI Resource.

You are authorized to use, copy and modify any individual TI Resource only in connection with the development of applications that include the TI product(s) identified in such TI Resource. NO OTHER LICENSE, EXPRESS OR IMPLIED, BY ESTOPPEL OR OTHERWISE TO ANY OTHER TI INTELLECTUAL PROPERTY RIGHT, AND NO LICENSE TO ANY TECHNOLOGY OR INTELLECTUAL PROPERTY RIGHT OF TI OR ANY THIRD PARTY IS GRANTED HEREIN, including but not limited to any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information regarding or referencing third-party products or services does not constitute a license to use such products or services, or a warranty or endorsement thereof. Use of TI Resources may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

TI RESOURCES ARE PROVIDED "AS IS" AND WITH ALL FAULTS. TI DISCLAIMS ALL OTHER WARRANTIES OR REPRESENTATIONS, EXPRESS OR IMPLIED, REGARDING TI RESOURCES OR USE THEREOF, INCLUDING BUT NOT LIMITED TO ACCURACY OR COMPLETENESS, TITLE, ANY EPIDEMIC FAILURE WARRANTY AND ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, AND NON-INFRINGEMENT OF ANY THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

TI SHALL NOT BE LIABLE FOR AND SHALL NOT DEFEND OR INDEMNIFY YOU AGAINST ANY CLAIM, INCLUDING BUT NOT LIMITED TO ANY INFRINGEMENT CLAIM THAT RELATES TO OR IS BASED ON ANY COMBINATION OF PRODUCTS EVEN IF DESCRIBED IN TI RESOURCES OR OTHERWISE. IN NO EVENT SHALL TI BE LIABLE FOR ANY ACTUAL, DIRECT, SPECIAL, COLLATERAL, INDIRECT, PUNITIVE, INCIDENTAL, CONSEQUENTIAL OR EXEMPLARY DAMAGES IN CONNECTION WITH OR ARISING OUT OF TI RESOURCES OR USE THEREOF, AND REGARDLESS OF WHETHER TI HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES.

You agree to fully indemnify TI and its representatives against any damages, costs, losses, and/or liabilities arising out of your non-compliance with the terms and provisions of this Notice.

This Notice applies to TI Resources. Additional terms apply to the use and purchase of certain types of materials, TI products and services. These include; without limitation, TI's standard terms for semiconductor products http://www.ti.com/sc/docs/stdterms.htm), evaluation modules, and samples (http://www.ti.com/sc/docs/sampterms.htm).

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2017, Texas Instruments Incorporated